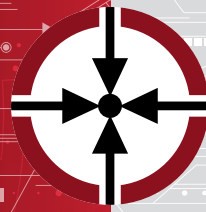


ESCP-MIS2

Medium Isolated
MEMS Capacitive Pressure Sensors



ES Systems has developed a series of pressure sensor modules targeting a variety of markets. Each module integrates an oil filled pressure capsule equipped with a medium isolation diaphragm that protects the MEMS capacitive pressure sensor die. The capsule housing is manufactured from stainless steel. The module can be fitted on a larger housing with a pressure port either by welding or by fitting and O-ring sealing.

The ESCP-MIS2 sensor incorporates the ES Systems capacitive MEMS sensor which is based on ES' proprietary SOI micro-fabrication TM30 process for absolute capacitive pressure sensors.

The digital output is fully calibrated and temperature compensated based on the internal temperature sensor and the factory calibration coefficients which are stored in the embedded memory.

The sensor provides high accuracy 32-bit pressure and temperature outputs.



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